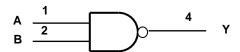


Pin Descriptions

Pin Name	Pin NO.	Description		
Α	1	Data Input		
В	2	Data Input		
GND	3	Ground		
Y	4	Data Output		
V _{CC}	5	Supply Voltage		

Logic Diagram



Function Table

Inpi	Output	
Α	В	Υ
Н	Н	L
L	Х	Н
Х	L	Н



Absolute Maximum Ratings (Note 2)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage applied to output in high or low state	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-20	mA
l _{OK}	Output Clamp Current (V _O < 0 or V _O > V _{CC})	±20	mA
Io	Continuous output current (V _O = 0 to V _{CC})	±25	mA
I _{CC}	Continuous current through V _{CC}	50	mA
I _{GND}	I _{GND} Continuous current through GND		mA
T_J	T _J Operating Junction Temperature		°C
T _{STG}	Storage Temperature	-65 to 150	°C

Notes: 2. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 3)

Symbol		Parameter	Min	Max	Unit
V _{CC}	Operating Voltage		2	5.5	V
V _{IH}		V _{CC} = 2V	1.5		
	High-level Input Voltage	$V_{CC} = 3V$	2.1		V
		V _{CC} = 5.5V	3.85		
		V _{CC} = 2V		0.5	
V_{IL}	Low-level input voltage	$V_{CC} = 3V$		0.9	V
		$V_{CC} = 5.5V$		1.65	
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	V _{CC}	V
		V _{CC} = 2V		-50	uA
I _{OH}	High-level output current	$V_{CC} = 3.3V \pm 0.3V$		-4	A
		$V_{CC} = 5V \pm 0.5V$		-8	mA mA
		V _{CC} = 2V		50	uA
I _{OL}	Low-level output current	$V_{CC} = 5V \pm 0.5V$		4	
		V _{CC} = 3V		8	mA
A+/A>/	Input transition rise or fall	V _{CC} = 3.3V ± 0.3 V		100	A /
Δt/ΔV	rate	$V_{CC} = 5V \pm 0.5V$		20	ns/V
T _A	Operating free-air temperature		-40	125	°C

Notes: 3. Unused inputs should be held at Vcc or Ground.



Electrical Characteristics

0		T () !!!!	.,		25°C		-40°C t	:o 85ºC	-40°C to	125°C	11.24
Symbol	Parameter	Test Conditions	V _{CC}	Min	Тур.	Max	Min	Max	Min	Max	Unit
		I _{OH} = -50μΑ	2V	1.9	2		1.9		1.9		
			3V	2.9	3		2.9		2.9		
V _{OH}	High Level		4.5V	4.4	4.5		4.4		4.4		V
	Output Voltage	$I_{OH} = -4mA$	3V	2.58			2.48		2.40		
		$I_{OH} = -8mA$	4.5V	3.94			3.8		3.70		
			2V			0.1		0.1		0.1	
		$I_{OL} = 50\mu A$	3V			0.1		0.1		0.1	
V _{OL}	Low Level		4.5V			0.1		0.1		0.1	V
	Output Voltage	$I_{OL} = 4mA$	3V			0.36		0.44		0.55	
		I _{OL} = 8mA	4.5V			0.36		0.44		0.55	
l _l	Input Current	V _I = 5.5 V or GND	0 to 5.5V			± 0.1		± 1		± 2	μΑ
I _{CC}	Supply Current	$V_I = 5.5V$ or GND $I_O=0$	5.5V			1		10		40	μΑ
Cı	Input Capacitance	$V_I = V_{CC} - or$ GND	5.5V		2.0	10		10		10	pF
θ_{JA}	Thermal Resistance	SOT25	(Note 4)		195						°C/W
ОЈД	Junction-to- Ambient	SOT353	(14016 4)		430						C/VV
Δ	Thermal Resistance	SOT25	(Note 4)		58						°C/W
θ _{JC}	Junction-to- Case	SOT353	(Note 4)		155						C/VV

Notes: 4. Test conditions for SOT25, and SOT353: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout

Switching Characteristics

$V_{CC} = 3.3V \pm 0.3$ (see Figure 1)

Parameter	From	TO		25°C		-40°C to 85°C		-40°C to 125°C		Unit	
	(Input)	(OUTPUT)		Min	Тур.	Max	Min	Max	Min	Max	
4 .	A or B	V	C _L =15pF	0.6	4.5	7.9	0.6	9.5	0.6	10.5	ns
^T pd	AUID	f	C _L =50pF	0.6	6.5	11.4	0.6	13.0	0.6	14.5	ns

$V_{CC} = 5V \pm 0.5V$ (see Figure 1)

Parameter	From	TO					25°C -40°C to 85°C		Unit		
	(Input)	(OUTPUT)		Min	Тур.	Max	Min	Max	Min	Max	
4 .	A or B	V	C _L =15pF	0.6	3.5	5.5	0.6	6.5	0.6	7.0	ns
t _{pd}	AUID	r	C _L =50pF	0.6	4.9	7.5	0.6	8.5	0.6	9.5	ns

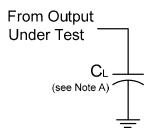


Operating Characteristics

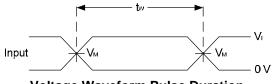
 $T_A = 25 \, {}^{\circ}C$

Parameter		Test Conditions	V _{CC} = 5 V Typ.	Unit
C _{pd}	Power dissipation capacitance	f = 1 MHz No Load	10	pF

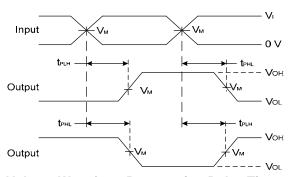
Parameter Measurement Information



Vcc	In	puts	V _M	C _L
•00	VI	t _r /t _f	▼ IVI	OL.
3.3V±0.3V	V _{CC}	≤3ns	V _{CC} /2	15pF
5V±0.5V	V _{CC}	≤3ns	V _{CC} /2	15pF
3.3V±0.3V	V _{CC}	≤3ns	V _{CC} /2	50pF
5V±0.5V	V _{CC}	≤3ns	V _{CC} /2	50pF



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Figure 1. Load Circuit and Voltage Waveforms

A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 1 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$



Ordering Information

T4AHC1G 00 XX - 7

Logic Device Function Package Packing

74 : Logic Prefix 00 : 2-Input W5 : SOT25 7 : Tape & Reel

AHC: 2 to 5.5V

Family 1G : One gate NAND-Gate SE: SOT353

	Device	Package	Packaging	7" Tape	and Reel
	Device	Code	(Note 5)	Quantity	Part Number Suffix
Pb ,	74AHC1G00W5-7	W5	SOT25	3000/Tape & Reel	-7
Pb ,	74AHC1G00SE-7	SE	SOT353	3000/Tape & Reel	-7

Notes: 5. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

Marking Information

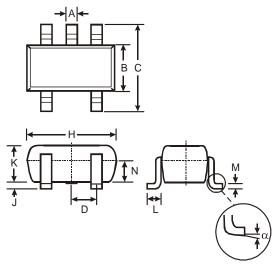
(Top View)

Part Number	Package	Identification Code
74AHC1G00W5	SOT25	YR
74AHC1G00SE	SOT353	YR



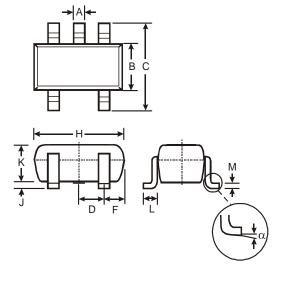
Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



20725							
SOT25							
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
O	2.70	3.00	2.80				
D			0.95				
H	2.90	3.10	3.00				
J	0.013	0.10	0.05				
K	1.00	1.30	1.10				
L	0.35	0.55	0.40				
M	0.10	0.20	0.15				
N	0.70	0.80	0.75				
α	0°	8°	_				
All D	imensi	ons in	mm				

(2) Package Type: SOT353



SOT353		
Dim	Min	Max
Α	0.10	0.30
В	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
Η	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
М	0.10	0.22
α	0°	8°
All Dimensions in mm		



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